

## ***Rudolph adds new in-line capability to NSX series***

**FLANDERS, N.J.**—Rudolph Technologies Inc. has added its proprietary WaferWoRx probing process analysis to the NSX Series of wafer inspection systems. This feature enables the machine to identify the root cause of probe test failure mechanisms, providing faster problem resolution and improved yield performance, according to the company.

“The probing process analysis capability of the WaferWoRx was a key factor in our decision to acquire Applied Precision’s Semiconductor Division in 2007,” said Paul F. McLaughlin, Rudolph’s chairman and chief executive officer. “We are pleased to announce the successful integration of WaferWoRx with our industry-leading NSX inspection platform, and we consider this milestone a testament to the success of the acquisition.”



*WaferWoRx has been added to Rudolph’s NSX Series.*

**The NSX System detects probe marks and generates location and size information as well as other parameters. WaferWoRx converts what has been a manual and time-consuming process of gathering scrub data from various tools, correlating the data, and then sifting through for trends to an automated data collection and analysis completed in a single step.**

According to Darren James, product manager for probe card test and analysis at Rudolph, “We have streamlined the approach to probing process analysis. What was once an off-line, one-off procedure that required extra time and equipment is now part of a high-throughput in-line system that can be used to identify the root cause of the failure and accelerate its resolution.”

**The WaferWoRx probe process analysis capability is available now on the NSX Series, and can be ordered as an upgrade for the NSX 100, NSX 105 or NSX 115 models.**

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